

## Molding Type Module IGBT, 2 in 1 Package, 1200 V and 100 A



Double INT-A-PAK

### FEATURES

- NPT IGBT technology
- 10  $\mu$ s short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(on)}$  with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

PRODUCT SUMMARY	
$V_{CES}$	1200 V
$I_C$ at $T_C = 80\text{ }^\circ\text{C}$	100 A
$V_{CE(on)}$ (typical) at $I_C = 100\text{ A}$ , $25\text{ }^\circ\text{C}$	3.10 V
Speed	8 kHz to 30 kHz
Package	Double INT-A-PAK
Circuit	Half bridge

### TYPICAL APPLICATIONS

- Switching mode power supplies
- Inductive heating
- Electronic welder

### DESCRIPTION

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welders and inductive heating.

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		1200	V
Gate to emitter voltage	$V_{GES}$		$\pm 20$	
Collector current	$I_C$	$T_C = 25\text{ }^\circ\text{C}$	200	A
		$T_C = 80\text{ }^\circ\text{C}$	100	
Pulsed collector current	$I_{CM}^{(1)}$	$t_p = 1\text{ ms}$	200	
Diode continuous forward current	$I_F$		100	
Diode maximum forward current	$I_{FM}^{(1)}$		200	
Maximum power dissipation	$P_D$	$T_J = 150\text{ }^\circ\text{C}$	1136	
Isolation voltage	$V_{ISOL}$	$f = 50\text{ Hz}$ , $t = 1\text{ min}$	2500	V

#### Note

(1) Repetitive rating: pulse width limited by maximum junction temperature.



IGBT ELECTRICAL SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$T_J = 25\text{ }^\circ\text{C}$	1200	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 25\text{ }^\circ\text{C}$	-	3.10	3.60	
		$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	3.45	-	
Gate to emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 1\text{ mA}, T_J = 25\text{ }^\circ\text{C}$	4.4	4.9	6.0	
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	-	400	nA

SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega,$ $V_{GE} = \pm 15\text{ V}, L = 200\text{ nH}, T_J = 25\text{ }^\circ\text{C}$	-	300	-	ns
Rise time	$t_r$		-	64	-	
Turn-off delay time	$t_{d(off)}$		-	340	-	
Fall time	$t_f$		-	105	-	
Turn-on switching loss	$E_{on}$		-	4.76	-	mJ
Turn-off switching loss	$E_{off}$		-	4.25	-	
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega,$ $V_{GE} = \pm 15\text{ V}, L = 200\text{ nH}, T_J = 125\text{ }^\circ\text{C}$	-	320	-	ns
Rise time	$t_r$		-	65	-	
Turn-off delay time	$t_{d(off)}$		-	350	-	
Fall time	$t_f$		-	132	-	
Turn-on switching loss	$E_{on}$		-	7.20	-	mJ
Turn-off switching loss	$E_{off}$		-	5.50	-	
Short circuit withstand time	$t_{SC}$	$T_J = 125\text{ }^\circ\text{C}$	-	-	10	$\mu\text{s}$
Input capacitance	$C_{ies}$	$V_{GE} = 0\text{ V}, V_{CE} = 20\text{ V}, f = 1.0\text{ MHz}$	-	8.45	-	nF
Output capacitance	$C_{oes}$		-	0.76	-	
Reverse transfer capacitance	$C_{res}$		-	0.31	-	
SC data	$I_{SC}$	$t_p \leq 10\text{ }\mu\text{s}, V_{GE} = \pm 15\text{ V}, V_{CC} = 600\text{ V},$ $V_{CEM} \leq 1200\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	900	-	
Internal gate resistance	$R_{GINT}$		-	2.4	-	$\Omega$
Stray inductance	$L_{CE}$		-	-	18	nH
Module lead resistance, terminal to chip	$R_{CC'+EE'}$		-	0.32	-	m $\Omega$

DIODE ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Diode forward voltage	$V_F$	$I_F = 100 \text{ A}$	$T_C = 25 \text{ }^\circ\text{C}$	-	1.82	2.22	V
			$T_C = 125 \text{ }^\circ\text{C}$	-	1.95	-	
Diode reverse recovery charge	$Q_{rr}$	$I_F = 100 \text{ A}, V_R = 600 \text{ V},$ $dI_F/dt = -1900 \text{ A}/\mu\text{s},$ $V_{GE} = -15 \text{ V}$	$T_C = 25 \text{ }^\circ\text{C}$	-	5.4	-	$\mu\text{C}$
			$T_C = 125 \text{ }^\circ\text{C}$	-	11.2	-	
Diode peak reverse recovery current	$I_{rr}$	$I_F = 100 \text{ A}, V_R = 600 \text{ V},$ $dI_F/dt = -1900 \text{ A}/\mu\text{s},$ $V_{GE} = -15 \text{ V}$	$T_C = 25 \text{ }^\circ\text{C}$	-	81	-	A
			$T_C = 125 \text{ }^\circ\text{C}$	-	101	-	
Diode reverse recovery energy	$E_{rec}$	$I_F = 100 \text{ A}, V_R = 600 \text{ V},$ $dI_F/dt = -1900 \text{ A}/\mu\text{s},$ $V_{GE} = -15 \text{ V}$	$T_C = 25 \text{ }^\circ\text{C}$	-	3.54	-	mJ
			$T_C = 125 \text{ }^\circ\text{C}$	-	6.57	-	

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	$T_J$			-40	-	150	$^\circ\text{C}$
Storage temperature range	$T_{Stg}$			-40	-	125	
Junction to case	$R_{thJC}$	IGBT		-	-	0.141	$^\circ\text{C}/\text{W}$
		Diode		-	-	0.225	
Case to sink	$R_{thCS}$	Conductive grease applied		-	0.035	-	
Mounting torque		Power terminal screw: M6		2.5 to 5.0			Nm
		Mounting screw: M6		3.0 to 6.0			
Weight				300			g

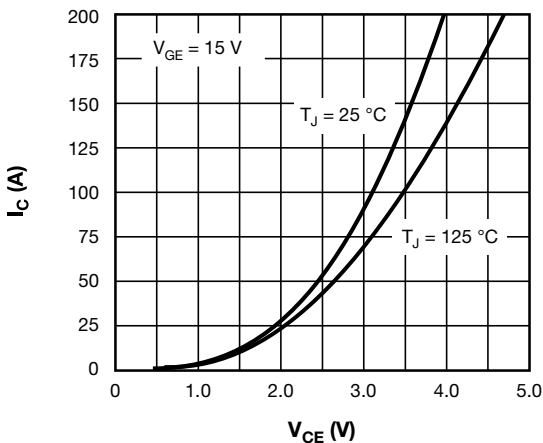


Fig. 1 - IGBT Typical Output Characteristics

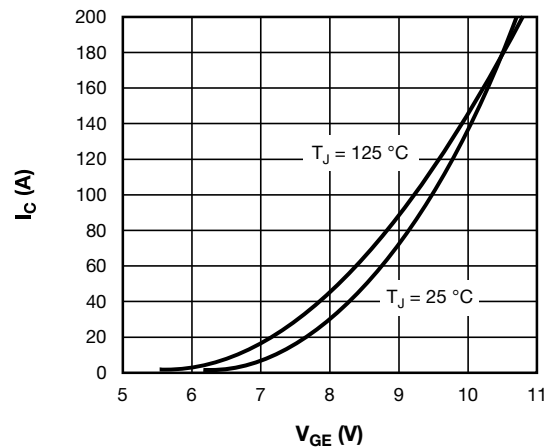


Fig. 2 - IGBT Typical Transfer Characteristics

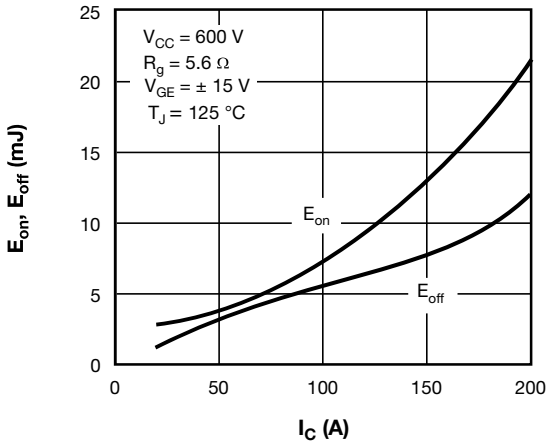


Fig. 3 - Switching Loss vs.  $I_C$

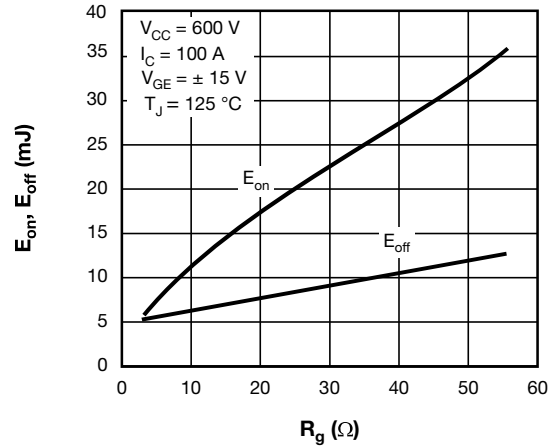


Fig. 4 - IGBT Switching Loss vs.  $R_g$

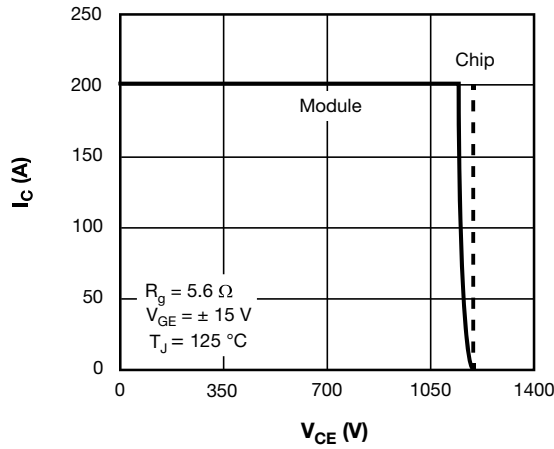


Fig. 5 - RBSOA

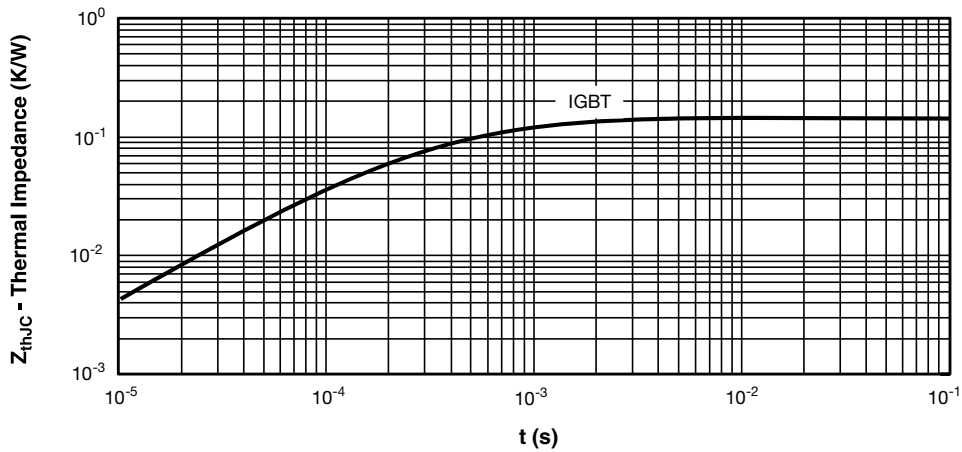


Fig. 6 - IGBT Transient Thermal Impedance

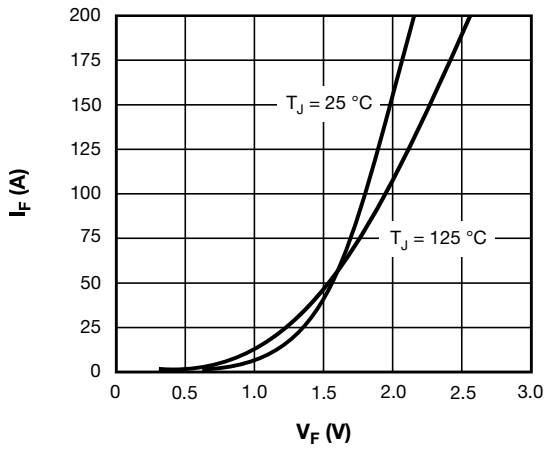


Fig. 7 - Diode Typical Forward Characteristics

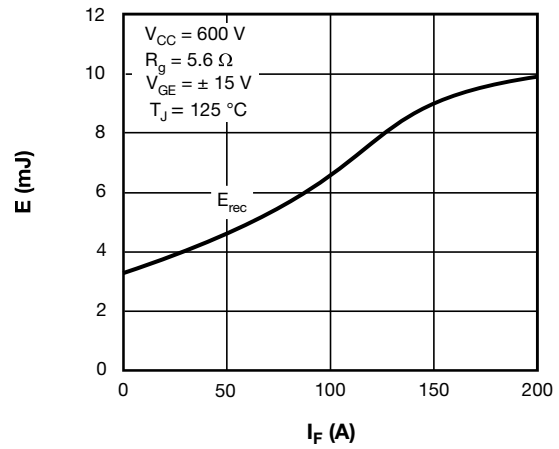


Fig. 8 - Diode Switching Loss vs.  $I_F$

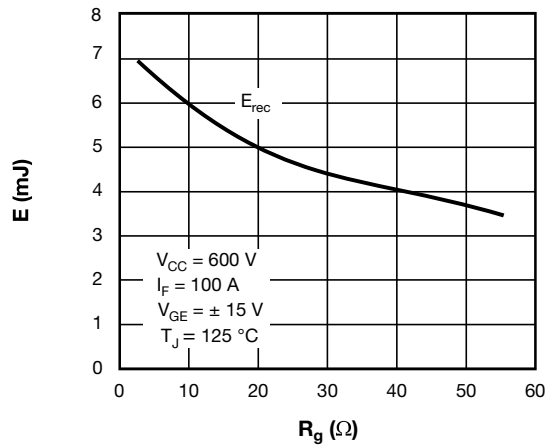


Fig. 9 - Diode Switching Loss vs.  $R_g$

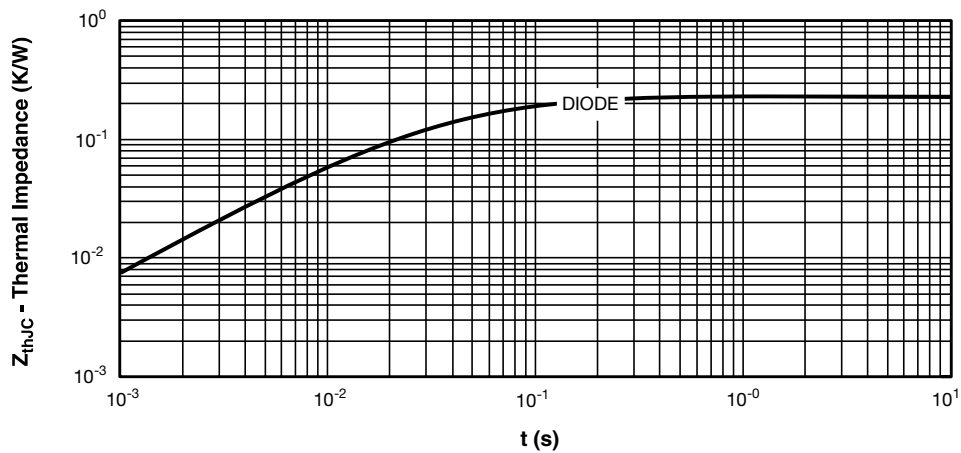
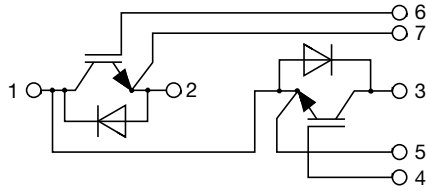


Fig. 10 - Diode Transient Thermal Impedance



**CIRCUIT CONFIGURATION**



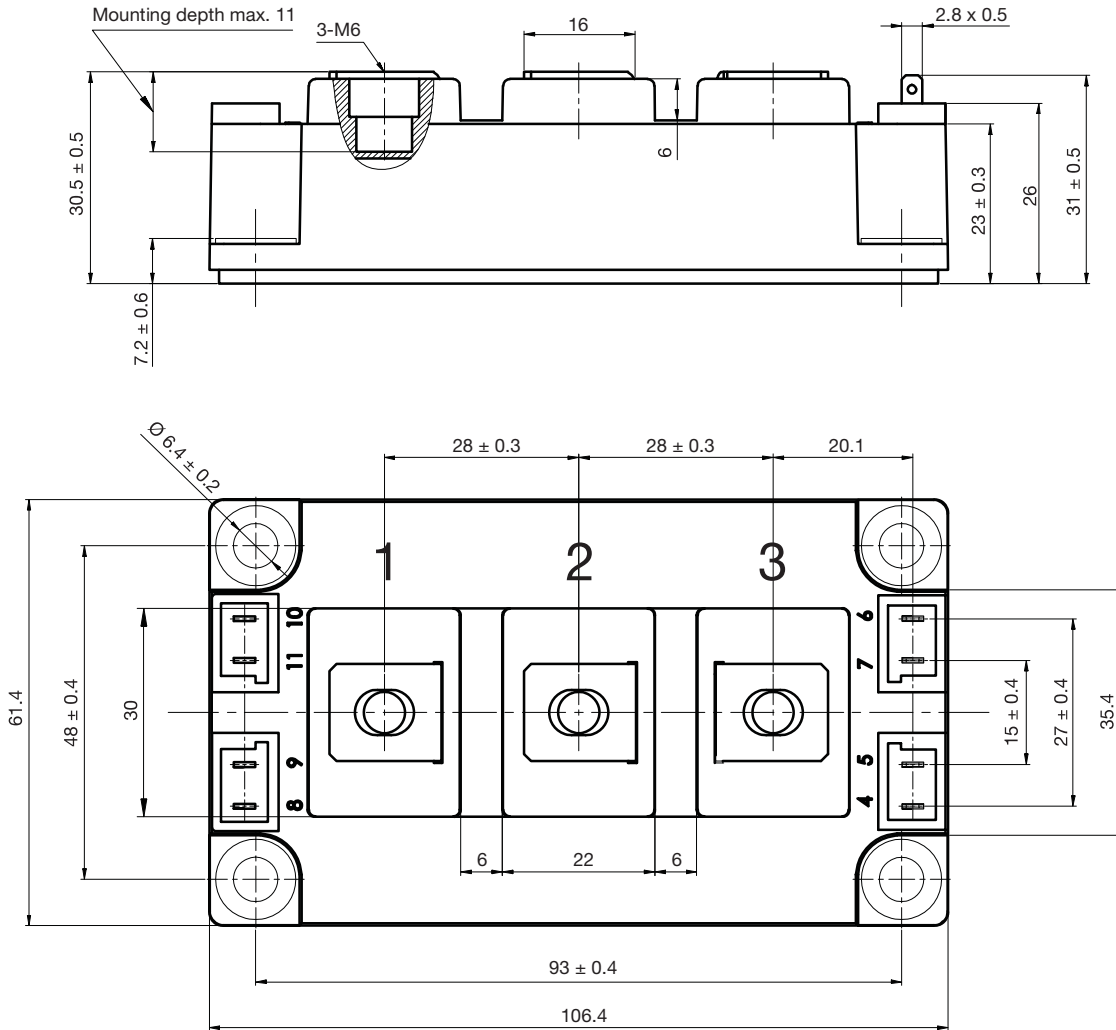
**LINKS TO RELATED DOCUMENTS**

<b>LINKS TO RELATED DOCUMENTS</b>	
Dimensions	<a href="http://www.vishay.com/doc?95525">www.vishay.com/doc?95525</a>



## Double INT-A-PAK

**DIMENSIONS** in millimeters (inches)





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